Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ** : Required Field*

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**17-03-2023**
Company Unique ID	**NL 008751171B01**		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	**MDG MD CHAMPION**	**Representative Title**	**MDG MD CHAMPION**
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
MDF Champion
Date: 2023.03.17
17:38:16 +01:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
M95P08-IXMNT/E	PHO7*5P081EB	A	3068	17-03-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	80.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
SON	NAC	8	Gull Wing	
Comment	Package : O7 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-10 Jun 2022	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**TRUE**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**PHO7*5P081EB**				6000000.0	999994.4
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	0.927	mg	supplier	die	Silicon (Si)	7440-21-3		0.870	mg	938511	10875
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	7551	88
				supplier	metallization	Copper (Cu)	7440-50-8		0.021	mg	22654	263
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.003	mg	3236	38
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1079	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.025	mg	26969	313
Lead-frame	M-011 Other inorganic materials	30.315	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.420	mg	970503	367756
				supplier	alloy	Iron (Fe)	7439-89-6		0.708	mg	23364	8853
				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1195	453
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	837	317
				supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	3761	1425
				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	241	91
				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	100	38
Die Attach	M-011 Other inorganic materials	2.460	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.214	mg	900000	27675
				supplier	glue or soft solder	acrylate	Proprietary		0.148	mg	60000	1845
				supplier	glue or soft solder	Methacrylate	Proprietary		0.093	mg	38000	1169
				supplier	glue or soft solder	acrylate	Proprietary		0.005	mg	2000	62
Wires	M-011 Other inorganic materials	0.062	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
Encapsulation	M-011 Other inorganic materials	46.234	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		3.178	mg	68728	39720
				supplier	Moulding Compound	Phenol Resin	Proprietary		2.118	mg	45819	26480
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		40.557	mg	877205	506963
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.212	mg	4582	2648
				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.169	mg	3666	2118
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	14
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0